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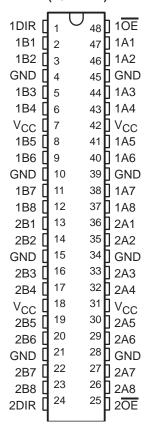
- **Members of the Texas Instruments** Widebus™ Family
- 3-State Outputs Drive Bus Lines or Buffer **Memory Address Registers**
- Flow-Through Architecture Optimizes PCB Layout
- Distributed V_{CC} and GND Configuration **Minimizes High-Speed Switching Noise**
- **EPIC** ™ (Enhanced-Performance Implanted CMOS) 1-µm Process
- 500-mA Typical Latch-Up Immunity at 125°C
- **Package Options Include Plastic Thin** Shrink Small-Outline (DGG) Package, 300-mil Shrink Small-Outline (DL) Package Using 25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Pin **Spacings**

description

The 'AC16245 are 16-bit bus transceivers organized as dual-octal noninverting 3-state transceivers designed for asynchronous two-way communication between data buses. The control function implementation minimizes external timing requirements

These devices allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending upon the logic level at the direction control (DIR) input. The output-enable input (OE) can be used to disable the devices so that the buses are effectively isolated.

54AC16245...WD PACKAGE 74AC16245...DGG OR DL PACKAGE (TOP VIEW)



The 74AC16245 is packaged in TI's shrink small-outline package, which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 54AC16245 is characterized for operation over the full military temperature range of –55°C to 125°C. The 74AC16245 is characterized for operation from -40°C to 85°C.

FUNCTION TABLE

	TROL UTS	OPERATION
OE	DIR	
L	L	B data to A bus
L	Н	A data to bus
Н	Χ	Isolation



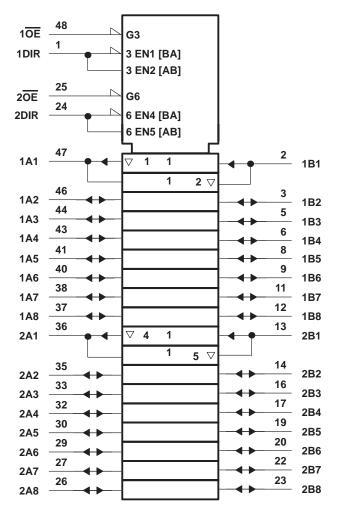
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STRUMENTS

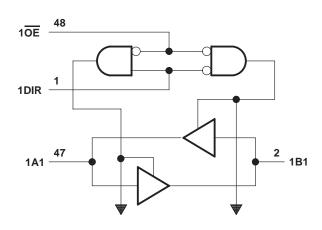
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logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



To Seven Other Transceivers

2DIR 24
2DIR 24
2A1 36
2B1

To Seven Other Transceivers



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 7 V
nput voltage range, V _I (see Note 1)	\dots -0.5 V to V _{CC} + 0.5 V
Output voltage range, VO (see Note 1)	-0.5 V to V _{CC} + 0.5 V
nput clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC})	
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$	±50 mA
Continuous current through V _{CC} or GND	±400 mA
Maximum power dissipation at T _A = 55°C (in still air) (see Note 2): DGG package	0.85 W
DL package .	1.2 W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

			54	AC1624	5	74AC16245			UNIT	
			MIN	NOM	MAX	MIN	NOM	MAX	UNII	
Vcc	Supply voltage (see Note 4)		3	5	5.5	3	5	5.5	V	
		VCC = 3 V	2.1			2.1				
٧ _{IH}	High-level input voltage	$V_{CC} = 4.5 \text{ V}$	3.15			3.15			v	
		$V_{CC} = 5.5 \text{ V}$	3.85			3.85				
		VCC = 3 V			0.9			0.9		
VIL	Low-level input voltage	V _{CC} = 4.5 V			1.35			1.35	V	
		V _{CC} = 5.5 V		JE.	1.65			1.65		
٧ _I	Input voltage		0	R	Vcc	0		Vcc	V	
٧o	Output voltage		0	5	Vcc	0		Vcc	V	
		VCC = 3 V	0		-4			-4		
ЮН	High-level output current	V _{CC} = 4.5 V	Q		-24			-24	mA	
		V _{CC} = 5.5 V			-24			-24		
		VCC = 3 V			12			12		
lOL	Low-level output current	V _{CC} = 4.5 V			24			24	mA	
		V _{CC} = 5.5 V			24			24		
Δt/Δν	Input transition rise or fall rate		0		10	0		10	ns/V	
TA	Operating free-air temperature		-55		125	-40		85	°C	

NOTES: 3. All unused pins (input and I/O) must be held high or low to prevent them from floating.

4. All V_{CC} and GND pins must be connected to the proper voltage power supply.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^{2.} The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST CONDITIONS	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	T,	Δ = 25°C		54AC16245		74AC16245		LINUT
PARAMETER		VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
		3 V	2.9			2.9		2.9		
	I _{OH} = -50 μA	4.5 V	4.4			4.4		4.4		
		5.5 V	5.4			5.4		5.4		
Voн	I _{OH} = -4 mA	3 V	2.58			2.48		2.48		V
	I _{OH} = -24 mA	4.5 V	3.94			3.8		3.8		
	IOH = -24 IIIA	5.5 V	4.94			4.8		4.8		1
	I _{OH} = -75 mA [†]	5.5 V				3.85	EV	3.85		
		3 V			0.1		0.1		0.1	
	I _{OL} = 50 μA	4.5 V			0.1		0.1		0.1	
		5.5 V			0.1	(0)	0.1		0.1	
VOL	I _{OL} = 12 mA	3 V			0.36	Pag	0.44		0.44	V
	I _{OL} = 24 mA	4.5 V			0.36	40	0.44		0.44	
	IOL = 24 IIIA	5.5 V			0.36	,	0.44		0.44	
	I _{OL} = 75 mA [†]	5.5 V					1.65		1.65	
lį	V _I = V _{CC} or GND	5.5 V			±0.1		±1		±1	μΑ
loz	V _I = V _{CC} or GND	5.5 V			±0.5		±5		±5	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			8		80		80	μΑ
Ci	V _I = V _{CC} or GND	5 V		4.5						pF
Co	$V_I = V_{CC}$ or GND	5 V		16						ÞΓ

T Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (see Figure 1)

PARAMETER	FROM	то	T _A = 25°C			54AC16245		74AC16245		UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII
^t PLH	A or B	B or A	2.5	7.6	10.4	2.5	11.9	2.5	11.9	no
^t PHL			3.1	9	12.3	3.1	13.5	3.1	13.5	ns
^t PZH	ŌĒ	A or B	2.8	8.6	11.8	2.8	13.2	2.8	13.2	no
^t PZL			3.9	12	16.2	3.9	18	3.9	18	ns
t _{PHZ}	ŌĒ	A or B	5.3	8.4	10.4	5.3	11.2	5.3	11.2	
t _{PLZ}	OE		4.4	7.7	9.7	4.4	10.3	4.4	10.3	ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (see Figure 1)

PARAMETER	FROM	то	T _A = 25°			54AC1	54AC16245		74AC16245	
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
t _{PLH}	A or B	B or A	2	4.6	6.9	2	7.9	2	7.9	ns
t _{PHL}			2.5	5.2	7.9	2.5	8.9	2.5	8.9	
^t PZH	ŌĒ	A or B	2.3	4.9	7.5	2.3	8.6	2.3	8.6	ns
tPZL			3	6.2	9.5	3	10.7	3	10.7	
t _{PHZ}	ŌĒ	A or B	5	7.2	9.1	5	9.8	5	9.8	no
^t PLZ	OE	AUIB	4.2	6.2	8.1	4.2	8.7	4.2	8.7	ns

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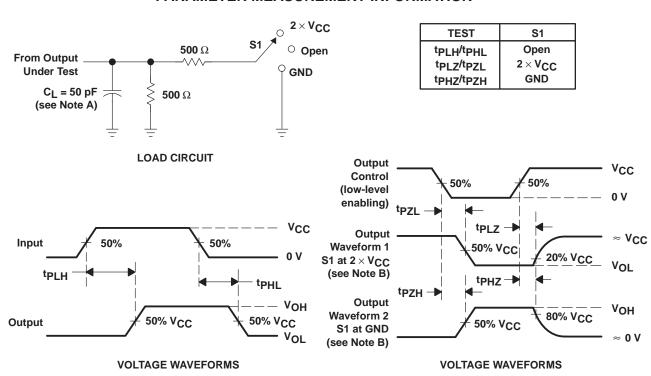


[‡] For I/O ports, the parameter IOZ includes the input leakage current.

operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CO	TYP	UNIT		
<u> </u>	C _{pd} Power dissipation capacitance per latch	Outputs enabled	C. 50 pF	f 1 MH I-	43	pF
Cpd		Outputs disabled	$C_L = 50 \text{ pF},$	f = 1 MHz	8	pr

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50~\Omega$, $t_f = 3~ns$, $t_f = 3~ns$.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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